Surface Mount Schottky Power Rectifier SMA Power Surface Mount Package

Employing the Schottky Barrier principle in a large area metal-to-silicon power diode. State of the art geometry features epitaxial construction with oxide passivation and metal overlay contact. Ideally suited for low voltage, high frequency rectification, or as free wheeling and polarity diodes in surface mount applications where compact size and weight are critical to the system.

- Small Compact Surface Mountable Package with J-Bent Leads
- Rectangular Package for Automated Handling
- Highly Stable Oxide Passivated Junction
- Very Low Forward Voltage Drop
- Guardring for Stress Protection
- Pb-Free Package is Available

Mechanical Characteristics:

- Case: Epoxy, Molded
- Weight: 70 mg (approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Max. for 10 Seconds
- Shipped in 12 mm tape, 5000 units per 13 inch reel
- Polarity: Cathode Lead Indicated by Polarity Band
- ESD Ratings: Machine Model = C Human Body Model = 3B
- Device Meets MSL 1 Requirements

MAXIMUM RATINGS

Rating	Symbol	Value	Unit		
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _R	40	V		
Average Rectified Forward Current (At Rated V _R , T _L = 100°C)	I _O 3.0		Α		
Non-Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions Halfwave, Single Phase, 60 Hz)	I _{FSM}	100	А		
Storage/Operating Case Temperature	T _{stg} , T _C	-55 to +150	°C		
Operating Junction Temperature	T _J	-55 to +125	°C		
Voltage Rate of Change (Rated V _R , T _J = 25°C)	dv/dt	10,000	V/μs		

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.



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SCHOTTKY BARRIER RECTIFIER 3.0 AMPERES 40 VOLTS





SMA CASE 403D PLASTIC

MARKING DIAGRAM



A34 = Device Code

A = Assembly Location L = Wafer Lot

Y = Year W = Work Week

ORDERING INFORMATION

Device	Package	Shipping [†]
MBRA340T3	SMA	5000/Tape & Reel
MBRA340T3G	SMA (Pb-Free)	5000/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

THERMAL CHARACTERISTICS

Characteristic	Symbol	Value	Unit
Thermal Resistance – Junction–to–Lead (Note 1) Thermal Resistance – Junction–to–Ambient (Note 1)	$R_{ hetaJL}$	15 81	°C/W

ELECTRICAL CHARACTERISTICS

Ī	Maximum Instantaneous Forward Voltage (Note 2)		V _F	$T_J = 25^{\circ}C$	T _J = 100°C	Volts
	3 ', ,	$(I_F = 3.0 \text{ A})$		0.450	0.390	
ĺ	Maximum Instantaneous Reverse Current		I _R	T _J = 25°C	T _J = 100°C	mA
		$(V_R = 40 V)$		0.3	15	

- Mounted on 2" Square PC Board with 1" Square Total Pad Size, PC Board FR4.
 Pulse Test: Pulse Width ≤ 250 μs, Duty Cycle ≤ 2.0%.

TYPICAL CHARACTERISTICS

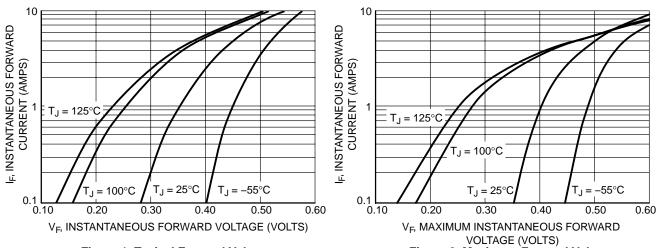


Figure 1. Typical Forward Voltage

Figure 2. Maximum Forward Voltage

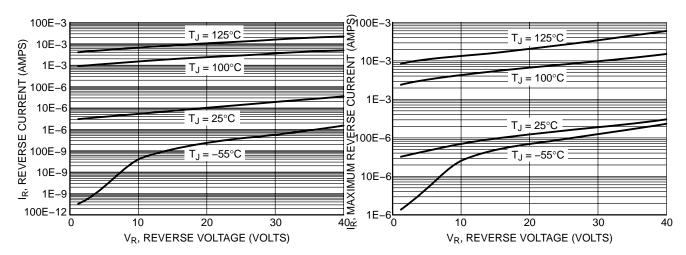


Figure 3. Typical Reverse Current

Figure 4. Maximum Reverse Current

TYPICAL CHARACTERISTICS

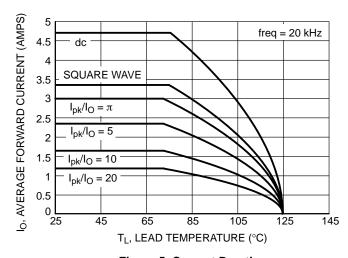


Figure 5. Current Derating

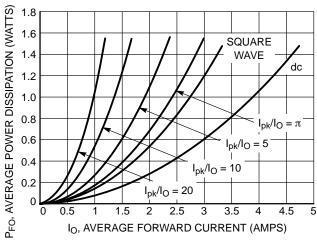


Figure 6. Forward Power Dissipation

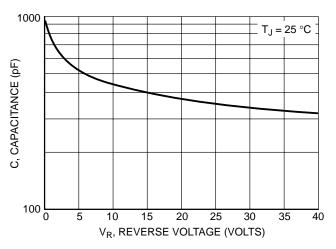


Figure 7. Capacitance

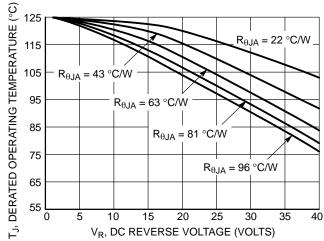


Figure 8. Typical Operating Temperature Derating

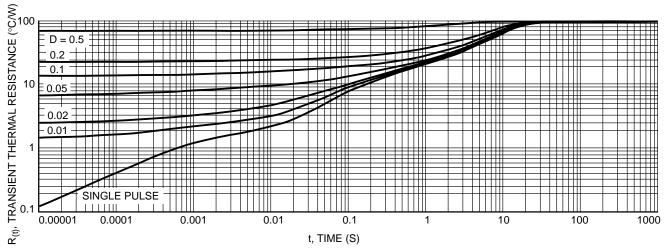


Figure 9. Thermal Response, Junction-to-Ambient (min pad)

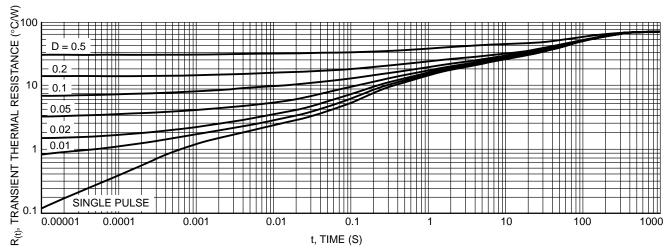
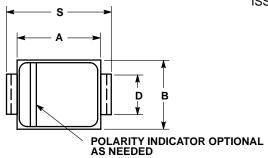


Figure 10. Thermal Response, Junction to Ambient (1 inch pad)

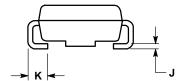
PACKAGE DIMENSIONS

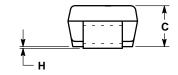
SMA CASE 403D-02 ISSUE A



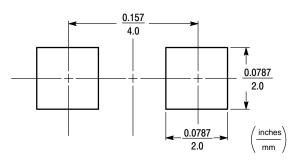
- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. 403D-01 OBSOLETE, NEW STANDARD IS 403D-02.

	INCHES MAX		MILLIMETERS		
DIM			MIN	MAX	
Α	0.160	0.180	4.06	4.57	
В	0.090	0.115	2.29	2.92	
C	0.075	0.095	1.91	2.41	
D	0.050	0.064	1.27	1.63	
Н	0.002	0.006	0.05	0.15	
J	0.006	0.016	0.15	0.41	
K	0.030	0.060	0.76	1.52	
S	0.190	0.220	4.83	5.59	





SOLDERING FOOTPRINT*



^{*}For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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